## 2x3mm QUAD-LEVEL LED INDICATOR

Part Number: WP914CK/4YDT Yellow

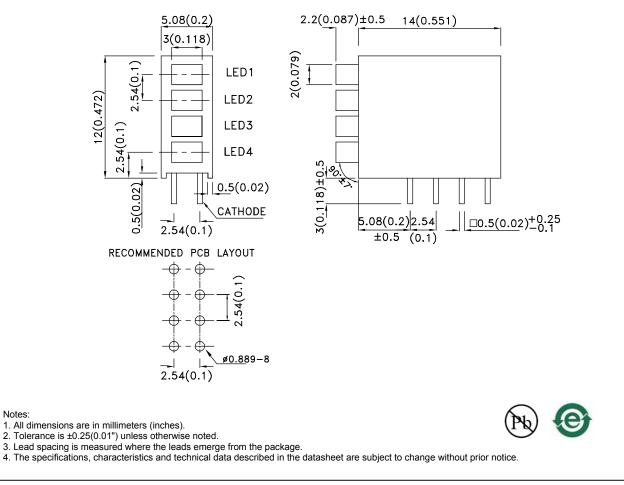
#### Features

- Quad-level design, save board space.
- Different color combination available .
- Black case enhances contrast.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

#### Description

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

#### **Package Dimensions**



SPEC NO: DSAF3500 APPROVED: WYNEC REV NO: V.6B CHECKED: Allen Liu DATE: MAR/28/2013 DRAWN: F.Cui PAGE: 1 OF 5 ERP: 1102002272

## Salaatian Cuida

Selection Guide					
Part No.	Dice	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Тур.	201/2
WP914CK/4YDT	Yellow (GaAsP/GaP)	Yellow Diffused	1.5	4	100°

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.
Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Yellow	590		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Yellow	588		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Yellow	35		nm	I⊧=20mA
С	Capacitance	Yellow	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Yellow	2.1	2.5	V	I⊧=20mA
lr	Reverse Current	Yellow		10	uA	VR = 5V

Notes: 1.Wavelength: +/-1nm. 2.Forward Voltage: +/-0.1V.

3.Wavelength value is traceable to the CIE127-2007 compliant national standards.

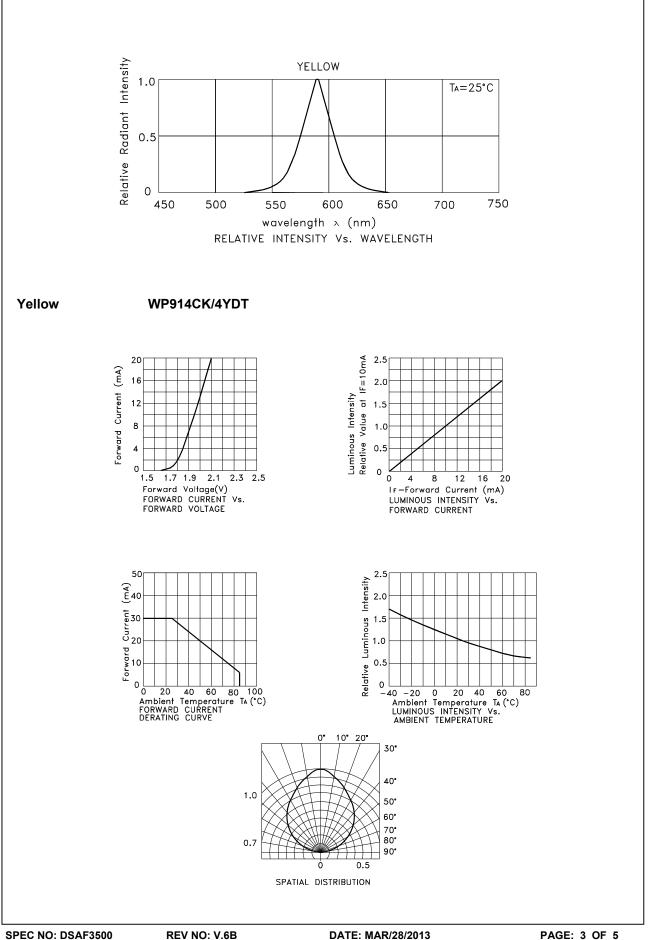
### Absolute Maximum Ratings at TA=25°C

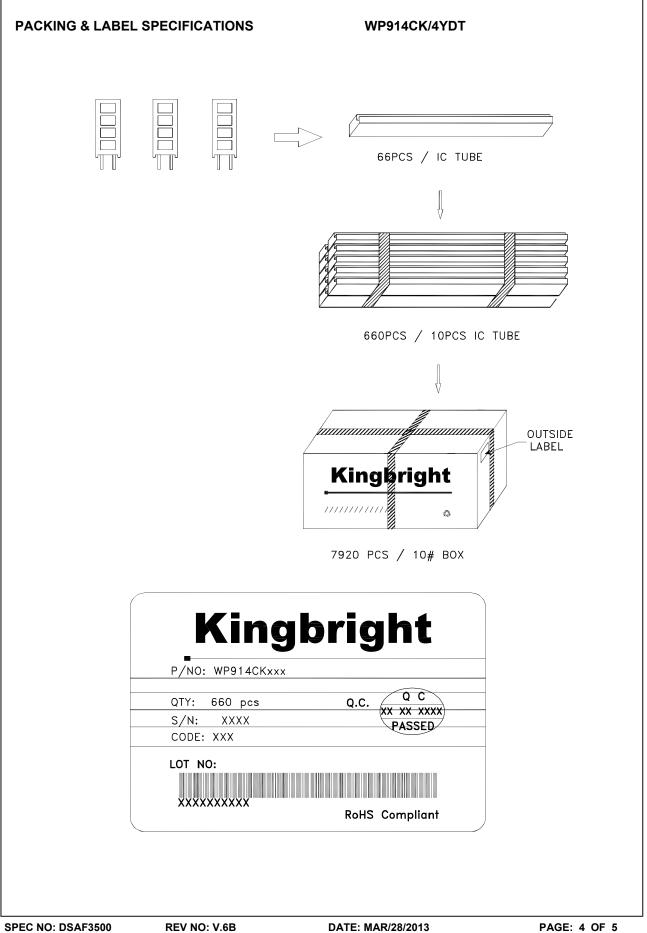
Parameter	Yellow	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	140	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.

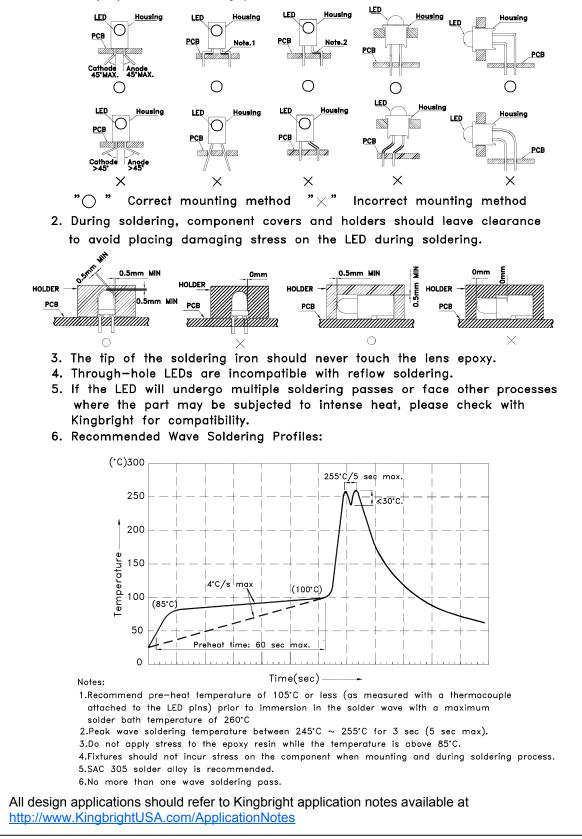
3. 5mm below package base.





### PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



DATE: MAR/28/2013 DRAWN: F.Cui